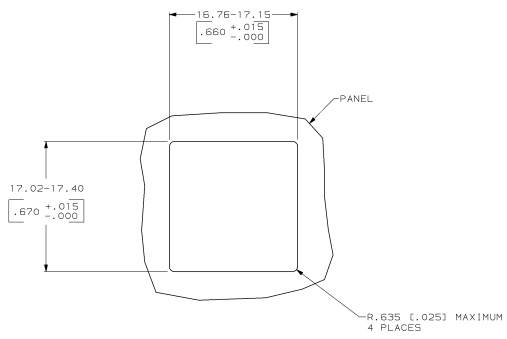
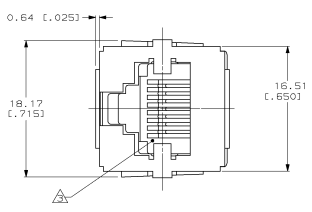
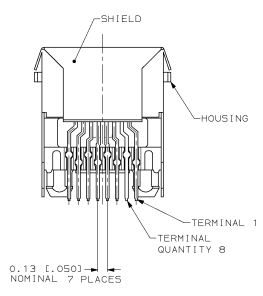
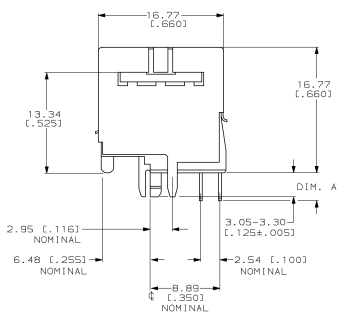


DRAWING MADE IN THIS WHOLE PROJECTION
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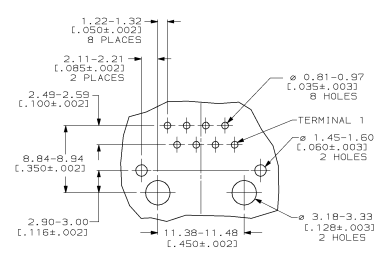
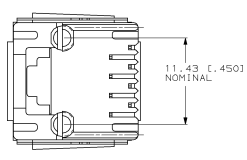
REV. NO.		DATE		DESCRIPTION	
AA	22			C	REV, EC 0210-0231-96



- △ DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- △ MATERIAL: HOUSING- POLYESTER MOLDING COMPOUND, BLACK; TERMINALS- 0.350 (.0138) THICK PHOS BRONZE PLATED WITH 1.27µm (.000050) MINIMUM THICK GOLD IN LOCALIZED AREA AND 3.81µm (.000150) MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm (.000050) MINIMUM THICK NICKEL UNDERPLATE. SHIELD- COPPER ZINC ALLOY PLATED WITH 2.03µm (.000080) MINIMUM THICK TIN-LEAD OVER 2.54µm (.000100) MINIMUM THICK COPPER UNDERPLATE.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLITIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.



SUGGESTED PANEL CUTOUT



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
NONCOMPONENT SIDE SHOWN

2.79-3.30 (.120±.010)	557969-2
2.92-3.94 (.135±.020)	557969-1

DIM. A		PART NO	
AMP AMP Incorporated Morrisburg, PA 17105-3608			
NAME		MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL STOPS, PANEL & PCB GROUNDS	
DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm (INCHES) TOLERANCES ON: 2 PL DEC ± 3 PL DEC ± ANGLES ±	DR 6-16-93 B. SIMPSON CHK 6-24-93 S. FOX APPD 6-24-93 J. TONE APPD 6-24-93 H. HIGBATH PRODUCT SPEC 108-1163	SIZE	DRAWING NO 00779 557969
FINISH	APPLICATION SPEC 114-2048	SCALE	4:1
WEIGHT		SHEET 1 OF 1	

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